

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	546	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38
L3	547	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38
L4	3508	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38

L5	422	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate with pads and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:39
L6	1	"20070190290"	US-PGPUB; USPAT	OR	ON	2009/12/07 01:29
L7	2	257/E	US-PGPUB; USPAT	OR	ON	2009/12/07 01:30
L8	101	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:30
L9	228	257/E33.068	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:31
L10	1656	257/680	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:33
L11	5017	257/98	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:35
L12	4049	257/99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:43

L13	2106	257/100	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:02
L14	1951	257/431	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:20
L15	2761	257/432	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:32
L16	2086	257/433	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:51
L17	836	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments or particles or powder) with (color\$3 or absorb\$3)	USPAT	OR	ON	2009/12/07 02:53
L18	335	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color \$3 or absorb\$3)	USPAT	OR	ON	2009/12/07 02:53
L19	59	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.4" near ("mm")	USPAT	OR	ON	2009/12/07 02:59
L20	114	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.1" near ("mm")	USPAT	OR	ON	2009/12/07 03:02

L21	1221	257/434	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 03:11
L22	51	(optoelectronic or LED or sensor or emit\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color\$3 or absorb \$3)	USPAT	OR	ON	2009/12/07 03:13
L23	3263	428/138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 03:16
S1	15	"4,936,808".pn. or "6,412,971".pn. or "6,373,188".pn. or "6,184,544".pn. or "6,335,545".pn. or "20040005728" or "20030160258" or "4,005,457".pn. or "20040041159" or "20020137245" or "6,291,841".pn. or "5,307,360".pn. or "20020096254"	US-PGPUB; USPAT	OR	OFF	2009/12/05 21:31
S2	7098	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (insulat\$3 or dielectric) and substrate	USPAT	OR	ON	2009/12/05 22:08
S3	1157	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate	USPAT	OR	ON	2009/12/05 22:09

S4	14	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) near (layer or film)	USPAT	OR	ON	2009/12/05 22:25
S5	42	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:30
S6	28	S5 not S4	USPAT	OR	ON	2009/12/05 22:30
S7	43	(optoelectronic or light or optical or LED or sensor) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:37
S8	1	S7 not S5	USPAT	OR	ON	2009/12/05 22:37

S9	43	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:38
S10	51	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:38
S11	9	S10 not S5	USPAT	OR	ON	2009/12/05 22:38
S12	19	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (pad)	USPAT	OR	ON	2009/12/05 22:41

S13	405	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/05 22:49
S14	1	("2004/0041159").URPN.	USPAT	OR	OFF	2009/12/05 23:14
S15	9	("5261013" "5323084" "5656847" "6153448" "6482664" "6504180" "6570180" "6593598" "6744194").PN. OR ("7078737").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/05 23:16
S16	543	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (within or cover\$3 or surround\$3 or embedded) with (insulat \$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/05 23:17
S17	138	S16 not S13	USPAT	OR	ON	2009/12/05 23:17

12/ 7/ 09 3:21:26 AM

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